

CALL FOR ABSTRACTS



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University of Dayton
Research Institute

9-12 February 2026 Palm Springs, California

The purpose of the High Temperature Polymeric Laminate (HIGH TEMPLE) Workshop is to review and discuss the latest technological developments in high-temperature polymer matrix composites with the aim of providing Government and Industry with the necessary technical data to effectively utilize these materials in aerospace applications. The material to be presented and discussed at High Temple Workshop sessions may contain information that is controlled by the International Traffic in Arms Regulations (ITAR) or the Export Administration Regulations (EAR).

Because of this, attendance will be restricted to U.S. citizens or permanent U.S. registered aliens (green card holders). All non-government employees must ensure that their employer is pre-registered with the Defense Logistics Service Center (DD Form 2345, Military Critical Technical Data Agreement). Attendance will be restricted to U.S. Government Agencies and private individuals or enterprises eligible to obtain export-controlled technical data.

Registration Fee: \$750

Includes the following:

- Light breakfasts Tuesday-Thursday
- Lunch on Tuesday and Wednesday
- Dinner on Wednesday evening
- Snacks and refreshments
- Access to proceedings

Accommodations:

Renaissance Palm Springs Hotel

888 E Tahquitz Canyon Way, Palm Springs, CA 92262
Phone: 760-322-6000

Website: Palm Springs Hotel Website

Group Rate: \$219 + state/local taxes and fees per night

A limited number of rooms will be available at the 2026 prevailing government per diem rate for government and US military traveling on official duty. Non-government employees are not eligible for the government rate.

Getting There:

Nearest Airports:

- Palm Springs Int. Airport (PSP) - 2 miles
- John Wayne Airport (SNA) - 98 miles
- Los Angeles Int. Airport (LAX) - 123 miles

Questions/Contacts:

For more information, contact:

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High Temple Website:

hightempleworkshop.com



Next Announcement: Invitation in October 2025

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High
Temple
2026

Palm Springs, CA



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Submission Instructions

ABSTRACTS ARE DUE MONDAY SEPTEMBER 22, 2025!

An abstract of the presentation material must be submitted no later than **September 22, 2025**. Abstracts received after this date will be considered for the program only on a space-available basis. Time provided for presentations will be 30 minutes and shall include sufficient time for interaction and questions from the audience and session chair. Presenters should be prepared to fully interact with the audience and session chair throughout the presentation. The audience is encouraged to pose questions to the presenter at any time during the presentation.

Special Interest Topic for 2026: Testing Standardization for High Temperature Materials & Composites

Additional topics of interest for the workshop include, but are not limited to:

1. High temperature polymer matrix composite (PMC) materials and processing developments
2. Novel high temperature polymers and resin chemistries
3. Advances in high temperature adhesive bonding materials and processes
4. Aerospace and missile applications for high temperature polymers, resins and composites
5. New and innovative applications for high temperature polymers, resins and composites
6. Advances in high temperature PMC mechanics, testing methodologies and modeling
7. Environmental aging and degradation mechanisms of high temperature polymers and PMCs
8. High temperature polymers for advanced manufacturing (including additive manufacturing)

Attendance Restriction

Attendance to the High Temple Workshop will be restricted to U.S. Government Agencies and private individuals or enterprises holding a valid DD 2345 Technical Share Agreement from the DoD and eligible to obtain export-controlled technical data. Therefore, **any material presented at High Temple must be DoD Distribution C or less restrictive** (i.e. public release). Any materials marked with a copyright statement will NOT be authorized for presentation at High Temple. By submitting an abstract to the High Temple Workshop, you are agreeing that the presented material does not exceed the limitations and further agree that the presented material can be placed in the High Temple Virtual Library and/or the DTIC database.

Please e-mail all abstracts in Microsoft Word format using the following attached abstract as an example. Please limit the abstract to 100 words or less. Send all abstracts to:

Kaitlin Rigitano
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phone: 937-255-3830
e-mail: kaitlin.rigitano@udri.udayton.edu

EXAMPLE

Title → **Butter-Mac 1000® Resin: The Solution to Many of the World's Problems**

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Sponsoring Organization → Sponsoring Organization: Vandelay Industries

Abstract (100 words or less)

ABSTRACT

Durability, producibility, and affordability are all key factors when launching a new line of composite resin systems. Butters Conglomerates and Excellence Incorporated have been evaluating several resin chemistries applicable for a variety of applications in the aerospace, maritime, and rehabilitation markets. Their final product, named Butter-Mac 1000®, yielded respectable flexure strengths, mediocre thermal oxidative stability, and superior marketability. At \$10,000 per pound, the affordability still needs work, but identification of affordable monomer sources should significantly decrease the cost. This presentation will provide the test results and provide a path forward for reducing costs.